L Number	Hits	Search Text	DB	Time stamp
	648	(216/24).CCLS.	USPAT;	2003/11/07 15:21
			US-PGPUB;	
			EPO; JPO;	
ļ			DERWENT;	
Í	<u> </u>		IBM_TDB	
_	358	((216/24).CCLS.) and ("<100>" or "<111>"	USPAT;	2003/11/07 15:23
	]	or "<110>")	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	ļ		IBM TDB	
_	19	((216/24).CCLS.) and ("<100>" or "<111>"	USPAT;	2003/11/07 15:23
	\	or "<110>") and (mirror adj array\$1)	US-PGPUB;	
	,		EPO; JPO;	
Ì			DERWENT;	
	[		IBM TDB	
_	117	((216/24).CCLS.) and ("<100>" or "<111>"	USPĀT;	2003/11/07 15:33
		or "<110>") and mirror\$1	US-PGPUB;	
	}		EPO; JPO;	
			DERWENT;	
	]		IBM TDB	
-	166	((216/24).CCLS.) and mirror\$1 and etch\$3	USPĀT;	2003/11/07 15:37
			US-PGPUB;	
)	1		EPO; JPO;	
			DERWENT;	
i			IBM TDB	
_	933	(mirror\$1 and etch\$3).clm. and ("<100>" or	USPAT;	2003/11/12 16:15
		"<111>" or "<110>")	US-PGPUB;	
ļ		, and the second	EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
-	193	(mirror\$1 and array\$1 and etch\$3).clm. and	USPĀT;	2003/11/12 16:16
	]	("<100>" or "<111>" or "<110>")	US-PGPUB;	
Į i	Į į		EPO; JPO;	(
			DERWENT;	
			IBM TDB	
	156	(mirror\$1 and etch\$3).clm. and ("<100>" or	USPĀT;	2003/11/07 15:25
	į į	"<111>" or "<110>").clm.	US-PGPUB;	
			EPO; JPO;	
ļ	•		DERWENT;	
			IBM_TDB	
]	45	(mirror\$1 and etch\$3 and (mask\$3 or	USPĀT;	2003/11/07 15:26
		\$5resist\$1)).clm. and ("<100>" or "<111>"	US-PGPUB;	
		or "<110>").clm.	EPO; JPO;	1
			DERWENT;	<b>\</b>
			IBM_TDB	
-	471	(((mirror\$1 or micro\$1mirror\$1) and	USPAT;	2003/11/07 15:40
	<b>j</b>	(array\$1 or micro\$1mechanical or	US-PGPUB;	
		micro\$lelectro\$lmechanical or MEMS)).ti.)	EPO; JPO;	1
		and (method\$1 or forming or making or	DERWENT;	
į		fabricating).ti.	IBM_TDB	
-	79	((((mirror\$1 or micro\$1mirror\$1) and	USPAT;	2003/11/07 16:27
		(array\$1 or micro\$1mechanical or	US-PGPUB;	1
		micro\$lelectro\$lmechanical or MEMS)).ti.)	EPO; JPO;	
		and (method\$1 or forming or making or	DERWENT;	1
]		fabricating).ti.) and ("<100>" or "<111>"	IBM_TDB	
		or "<110>")		0000/11/07 15 10
-	62	((((mirror\$1 or micro\$1mirror\$1) and	USPAT;	2003/11/07 15:32
•	{	(array\$1 or micro\$1mechanical or	US-PGPUB;	\
		micro\$lelectro\$lmechanical or MEMS)).ti.)	EPO; JPO;	1
		and (method\$1 or forming or making or	DERWENT;	
		fabricating).ti.) and ("<100>" or "<111>"	IBM_TDB	
		or "<110>") and etch\$3		00002/11/07 15 55
_	13	((216/24).CCLS.) and ("<100>" or "<111>"	USPAT;	2003/11/07 15:37
		or "<110>") and mirror\$1 and (alignment	US-PGPUB;	
	ļ	adj (feature\$1 or mark\$1))	EPO; JPO;	Į.
			DERWENT;	
			IBM_TDB	

_	167	((216/24).CCLS.) and \$5mirror\$1 and etch\$3		2003/11/07	16:18
	-		US-PGPUB; EPO; JPO;		
			DERWENT;		
			IBM_TDB		
_	3	1 ( , = - , )	USPAT;	2003/11/07 1	15:39
		adj plane\$1)	US-PGPUB;		
			EPO; JPO; DERWENT;		
			IBM TDB		
-	91	((216/24).CCLS.) and mirror\$1 and plane\$1	USPAT;	2003/11/07 1	15:39
			US-PGPUB;		
			EPO; JPO; DERWENT;		
			IBM TDB		
_	41	'	USPAT;	2003/11/07 1	15:42
		and plane\$1	US-PGPUB;		
			EPO; JPO; DERWENT;		
			IBM TDB		
_	1636	((\$6mirror\$1) and (array\$1 or MEMS)).ti.	USPAT;	2003/11/10 1	l6:01
			US-PGPUB;		ì
			EPO; JPO; DERWENT;		
			IBM TDB		
_	46	((\$6mirror\$1) and (array\$1 or MEMS)).ti.	USPAT;	2003/11/07 1	6:21
		and plane\$1 and etch\$3	US-PGPUB; EPO; JPO;		
			DERWENT;		
]	1		IBM TDB		
_	29		USPAT;	2003/11/07 1	5:44
		and plane\$1 and mask\$3	US-PGPUB;		
			EPO; JPO; DERWENT;		
			IBM TDB		1
_	52	' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPĀT;	2003/11/07 1	5:44
		and plane\$1 and etch\$3) or (((\$6mirror\$1) and (array\$1 or MEMS)).ti. and plane\$1 and	US-PGPUB; EPO; JPO;		
		mask\$3)	DERWENT;		j
			IBM TDB		ľ
	658	2002-405915.NRAN. (359/223).CCLS.	DERWENT	2003/11/07 1	
	0,50	(3337223).0013.	USPAT; US-PGPUB;	2003/11/07 1	6:21
			EPO; JPO;		
			DERWENT;		
i _	527	(359/224).CCLs.	IBM_TDB	0000/11/07 1	
İ		(0/20//0000)	USPAT; US-PGPUB;	2003/11/07 1	ρ:Z1 [
			EPO; JPO;		
1			DERWENT;		1
_	167	(359/225).CCLS.	IBM_TDB USPAT;	2003/11/07 1	6.21
		· · · · · · · · · · · · · · · · · · ·	US-PGPUB;	2003/11/0/ 1	U.41
			EPO; JPO;		1
			DERWENT;		
_	206	(359/226).CCLS.	IBM_TDB USPAT;	2003/11/07 1	6.22
		·	US-PGPUB;	2003/11/07 1	V. ZZ
			EPO; JPO;		
			DERWENT;		
	1216	(257/431).CCLS.	IBM_TDB USPAT;	2003/11/07 16	6.24
ļ			US-PGPUB;		V. Z. I
			EPO; JPO;		
			DERWENT; IBM TDB		
-	1150	(257/432).CCLS.	USPAT;	2003/11/07 16	5:24
			US-PGPUB;		
			EPO; JPO;		
	1		DERWENT; IBM TDB		}
			TDM IDD		

			Lucian	10000 /01 /07 15 05
_	805	(257/433).CCLS.	USPAT;	2003/11/07 16:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	İ
			IBM_TDB	
-	924	(257/435).CCLS.	USPAT;	2003/11/07 16:25
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	ļ
	1		IBM TDB	
-	819	(257/443).CCLS.	USPAT;	2003/11/07 16:25
			US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
			IBM TDB	
	79	((((mirror\$1 or micro\$1mirror\$1) and	USPAT;	2003/11/07 16:28
	1	(array\$1 or micro\$1mechanical or	US-PGPUB;	
		micro\$lelectro\$lmechanical or MEMS)).ti.)	EPO; JPO;	1
		and (method\$1 or forming or making or	DERWENT;	
(	Į	fabricating).ti.) and ("{100}" or "{111}"	IBM TDB	
1		or "{110}")	12:1-12:5	
	358	((216/24).CCLS.) and ("{100}" or "{111}"	USPAT;	2003/11/07 16:30
	330	or "{110}")	US-PGPUB;	2003/11/07 10:30
	[	Or (110)	EPO; JPO;	}
			DERWENT;	1.
	1		IBM TDB	
	1.00	(65minnan61 and (8(10018 an 8(1111)8 an		2002/11/10 16:22
	162	(\$6mirror\$1 and ("{100}" or "{111}" or	USPAT;	2003/11/10 16:23
		"{110}") and etch\$3).clm.	US-PGPUB;	1.
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	1 0000 400 400 00 00
-	30		USPAT;	2003/11/07 16:33
		etch\$3).clm.	US-PGPUB;	
ļ			EPO; JPO;	1
			DERWENT;	
			IBM_TDB	
	270	(\$6mirror\$1 and (plane\$1) and etch\$3).clm.	USPAT;	2003/11/07 16:34
i			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
į			IBM_TDB	1
-	9181	((\$6mirror\$1 or optical) and (array\$1 or	USPAT;	2003/11/10 16:03
		MEMS)).ti.	US-PGPUB;	
			EPO; JPO;	
[			DERWENT;	<u> </u>
]			IBM TDB	
-	1381	(((\$6mirror\$1 or optical) and (array\$1 or	USPĀT;	2003/11/10 16:02
		MEMS)).ti.) and plane\$1	US-PGPUB;	
		-	EPO; JPO;	
<b>j</b>			DERWENT;	
			IBM TDB	
-	217	(((\$6mirror\$1 or optical) and (array\$1 or	USPAT;	2003/11/10 16:03
		MEMS)).ti.) and plane\$1 and etch\$3	US-PGPUB;	
		•	EPO; JPO;	
i			DERWENT;	
[			IBM TDB	<u> </u>
_	6196	(optical adj switch).ti.	USPAT;	2003/11/10 16:04
	,		US-PGPUB;	
	į		EPO; JPO;	
}			DERWENT;	)
			IBM TDB	1
_	164	(optical ad; switch).ti. and plane\$1 and	USPAT;	2003/11/10 16:04
į		etch\$3	US-PGPUB;	
		, 0 - 2 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	370	((((\$6mirror\$1 or optical) and (array\$1 or	USPAT;	2003/11/10 16:04
]	3,0	MEMS)).ti.) and plane\$1 and etch\$3) or	US-PGPUB;	2000/11/10 10:04
ĺ		((optical adj switch).ti. and plane\$1 and	EPO; JPO;	
I				1
		a t a b & 2 \		
		etch\$3)	DERWENT; IBM TDB	

-	3	(("5828485") or ("5953151")).PN.	USPAT;	2003/11/10 16:29
			US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
_	112	(torsion adj beam) and (address adj	USPAT;	2003/11/10 17:23
	1	electrode)	US-PGPUB;	2003/11/10 17.23
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	5683	spatial adj light adj modulator\$1	USPAT;	2003/11/10 16:37
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	311	(spatial adj light adj modulator\$1).ti.	USPĀT;	2003/11/10 16:39
ļ		and ("<100>" or "<111>" or "<110>" or	US-PGPUB;	2003/11/10 10:33
		"{100}" or "{111}" or "{110}")	EPO; JPO;	
			DERWENT;	
i	1.4		IBM_TDB	
-	14	1 , 7 , -, -, -, -, -, -, -, -, -, -, -, -, -	USPAT;	2003/11/10 16:40
		and ("<100>" or "<111>" or "<110>" or "(100)" or "(111)" or "(110)").clm.	US-PGPUB;	
		(100) OF (111) OF (110) J.CIM.	EPO; JPO; DERWENT;	
			IBM TDB	
-	65	(MEMS or micromechanical).ti. and ("<100>"	USPAT;	2003/11/10 16:41
		or "<111>" or "<110>" or "{100}" or	US-PGPUB;	
		"{111}" or "{110}").clm.	EPO; JPO;	
1	İ		DERWENT;	
_	201	(66minnon01) hi and (84100) 8 and 84111	IBM_TDB	
	201	(\$6mirror\$1).ti. and ("<100>" or "<111>" or "<110>" or "{110}" or "{111}" or	USPAT;	2003/11/10 16:46
		"{110}").clm.	US-PGPUB; EPO; JPO;	
		(110) / • 01	DERWENT;	
			IBM TDB	
-	48	1 , 1 , , , , , , , , , , , , , , , , ,	USPAT;	2003/11/10 16:48
		and (torsion adj (beam or hinge))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	101	(torsion adj hinge) and (address adj	IBM_TDB USPAT;	2003/11/10 17:23
		electrode)	US-PGPUB;	2003/11/10 17:23
,		,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	155	, , ,	USPAT;	2003/11/10 17:27
		electrode)) or ((torsion adj beam) and	US-PGPUB;	
		(address adj electrode))	EPO; JPO; DERWENT;	
			IBM TDB	
ļ —	746	(\$6mirror\$1 and (beam or hinge) and	USPAT;	2003/11/12 13:24
	ļ	("<100>" or "<111>" or "<110>" or "{100}"	US-PGPUB;	
		or "{111}" or "{110}")).clm.	EPO; JPO;	
			DERWENT;	
[	1 173 1	(mi anami nua 202	IBM_TDB	
-	171	(micromirror\$1 or micro-mirror\$1).ti. and	USPAT;	2003/11/10 17:30
		("<100>" or "<111>" or "<110>" or "{100}" or "{111}" or "{110}")	US-PGPUB;	
		~~ (***) Or (IIO)	EPO; JPO; DERWENT;	
			IBM TDB	
-	675	(micromirror\$1 or micro-mirror\$1).ti.	USPAT;	2003/11/10 17:38
			US-PGPUB;	
			EPO; JPO;	
	ļ		DERWENT;	
_	71	(\$6mirror\$1 and (beam or hinge) and mask\$3	IBM_TDB	2002/11/12 12 22
	′ -	and ("<100>" or "<111>" or "<110>" or	USPAT; US-PGPUB;	2003/11/12 13:28
	-	"{100}" or "{111}" or "{110}")).clm.	EPO; JPO;	
	İ	, ( ) //· Q2m·	DERWENT;	
			IBM TDB	

	467	(\$6mirror\$1 and (beam or hinge) and mask\$3 and plane\$1).clm.	USPAT; US-PGPUB;	2003/11/12 13:29
			EPO; JPO; DERWENT; IBM TDB	
-	27	(\$6mirror\$1 and (beam or hinge) and mask\$3 and plane\$1 and etch\$3).clm.	USPAT; US-PGPUB;	2003/11/12 13:30
			EPO; JPO; DERWENT;	
_	90	(	IBM_TDB USPAT;	2003/11/12 13:30
	İ	and plane\$1 and (MEMS or array\$1)).clm.	US-PGPUB; EPO; JPO; DERWENT;	
_	1351	(spatial adj light adj modulator\$1).ti.	IBM_TDB USPAT;	2003/11/12 13:34
			US-PGPUB; EPO; JPO;	2000, 11, 12 13.31
			DERWENT; IBM_TDB	
_	10	(spatial adj light adj modulator\$1) and (mask\$3 and etch\$3 and plane\$1).clm.	USPAT; US-PGPUB; EPO; JPO;	2003/11/12 16:13
			DERWENT; IBM TDB	
	14	(light adj modulator\$1) and (mask\$3 and etch\$3 and plane\$1).clm.	USPĀT; US-PGPUB;	2003/11/12 13:36
			EPO; JPO; DERWENT;	
-	7	(spatial adj light adj modulator\$1).ti. and (etch\$3 and plane\$1).clm.	IBM_TDB USPAT; US-PGPUB;	2003/11/12 13:38
			EPO; JPO; DERWENT;	
_	0	(MEMS.).ti. and (mask\$3 and etch\$3 and plane\$1).clm.	IBM_TDB USPAT;	2003/11/12 13:40
	į	pranevi).Cim.	US-PGPUB; EPO; JPO; DERWENT;	
_	12	(MEMS or \$6mirror\$1).ti. and (mask\$3 and	IBM_TDB USPAT;	2003/11/12 13:42
		etch\$3 and plane\$1).clm.	US-PGPUB; EPO; JPO;	
_	11	(micromechanical or microstructure\$1).ti.	DERWENT; IBM_TDB USPAT;	2003/11/12 13:42
		and (mask\$3 and etch\$3 and plane\$1).clm.	US-PGPUB; EPO; JPO;	2003/11/12 13.42
_	155	(438/24).CCLS.	DERWENT; IBM_TDB	0000/11/10 11 55
		(450/24).CCDS.	USPAT; US-PGPUB; EPO; JPO;	2003/11/12 14:55
			DERWENT; IBM_TDB	
-	269	(438/34).CCLS.	USPAT; US-PGPUB;	2003/11/12 15:13
			EPO; JPO; DERWENT; IBM TDB	
_	516	(438/40).CCLS.	USPĀT; US-PGPUB;	2003/11/12 16:00
			EPO; JPO; DERWENT;	
_	170	(438/66).CCLS.	IBM_TDB USPAT; US-PGPUB;	2003/11/12 14:57
			EPO; JPO; DERWENT;	
			IBM TDB	

		200	(420/60) 0010	LIOT 3 M	10000 /11 /10 11 57
_		200	(438/69).CCLS.	USPAT; US-PGPUB;	2003/11/12 14:57
	ļ			EPO; JPO;	
				DERWENT;	
		0.00	(400 (50) 500	IBM_TDB	
_		237	(438/72).CCLS.	USPAT;	2003/11/12 14:58
				US-PGPUB; EPO; JPO;	
				DERWENT;	
	ļ			IBM TDB	
-	į	381	(438/401).CCLS.	USPAT;	2003/11/12 14:58
				US-PGPUB;	
				EPO; JPO; DERWENT;	
				IBM TDB	
_		778	(438/400).CCLS.	USPĀT;	2003/11/12 16:01
				US-PGPUB;	
				EPO; JPO;	1
				DERWENT;	
_		113	(438/405).CCLS.	IBM_TDB USPAT;	2003/11/12 16:01
		110	(43074037,0000.	US-PGPUB;	2003/11/12 10:01
				EPO; JPO;	
				DERWENT;	
		261	(420/324) 0070	IBM_TDB	0000/11/100
-		364	(438/734).CCLS.	USPAT; US-PGPUB;	2003/11/12 16:11
				EPO; JPO;	
				DERWENT;	
-				IBM_TDB	
-		9	((438/734).CCLS.) and plane\$1.clm.	USPAT;	2003/11/12 16:12
	+			US-PGPUB;	İ
	İ			EPO; JPO; DERWENT;	
	}			IBM TDB	
-		7	((438/400).CCLS.) and plane\$1.clm.	USPAT;	2003/11/12 16:12
				US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
_		38	(spatial adj light adj modulator\$1) and	USPĀT;	2003/11/12 17:44
			(mask\$3 and etch\$3).clm.	US-PGPUB;	
				EPO; JPO;	
				DERWENT;	
_	J	798	(light adj valve).clm. and ("<100>" or	IBM_TDB USPAT;	2003/11/12 16:16
	1	- •	"<111>" or "<110>")	US-PGPUB;	
	ł			EPO; JPO;	
				DERWENT;	
_		205	(\$6mirror\$1 and array\$1 and etch\$3).clm.	IBM_TDB USPAT;	2003/11/12 16:20
1		200	and ("<100>" or "<111>" or "<110>")	US-PGPUB;	5003/11/15 10:50
				EPO; JPO;	
				DERWENT;	
_		177	/cominmont and tourism a	IBM_TDB	0000/11/10 10 01
-		177	(\$6mirror\$1 and torsion).clm. and (plane\$1)	USPAT; US-PGPUB;	2003/11/12 16:21
			(2200042)	EPO; JPO;	
				DERWENT;	[
		, <u> </u>		IBM_TDB	
-		134	(micromirror\$1 and (KOH or (potassium adj	USPĀT;	2003/11/12 17:58
			hydroxide)))	US-PGPUB;	
				EPO; JPO; DERWENT;	
				IBM TDB	
-		2	compensation adj rectangle	USPĀT;	2003/11/12 17:46
				US-PGPUB;	
		-		EPO; JPO; DERWENT;	
				IBM TDB	
<b></b>	L				<u>, , , , , , , , , , , , , , , , , , , </u>

	12	(micromirror\$1 same (bulk adj	USPAT;	2003/11/12 18:00
		micromachining))	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
_	52	<pre>(mirror\$1 same (bulk adj micromachining))</pre>	USPAT;	2003/11/12 18:00
			US-PGPUB;	ļ
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

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